



RF360  
Europe GmbH

## Data sheet

### BAW filter

WLAN 2G; Bluetooth

Part number:	B4346
Ordering code:	B39242B4346P810
Date:	April 01, 2021
Version:	2.2

DCN: 80-PA243-558 Rev. A

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## 1 Application

- Low-loss BAW RF single filter for Bluetooth/WLAN 2G with LTE Band 7 / Band 40 / Band 41 coexistence for Automotive telematics
- WLAN 2G; Bluetooth: pass band 2401.5 – 2480.9 MHz
- Usable pass band 79.4 MHz
- Excellent insertion loss
- High out of band selectivity
- Filter impedance 50  $\Omega$
- Excellent B7 attenuation

## 2 Features

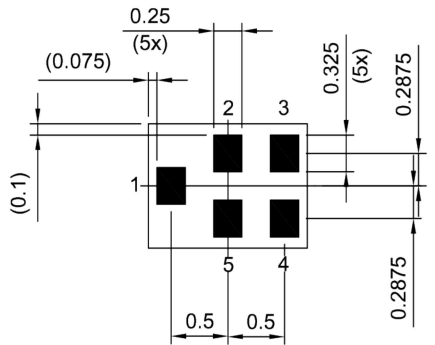
- Package size 1.4 $\pm$ 0.1 mm  $\times$  1.1 $\pm$ 0.1 mm
- Package height 0.45 mm (max.)
- Approximate weight 2 mg
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Filter surface passivated
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level 2a (MSL2a)
- AEC-Q200 qualified component family (Grade 3: -40  $^{\circ}$ C to +85  $^{\circ}$ C)



**Figure 1:** Picture of component with example of product marking.

### 3 Package

BOTTOM VIEW



Pad and pitch tolerance  $\pm 0.05$

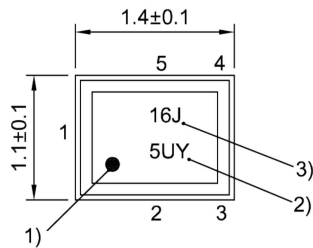
### 4 Pin configuration

- 1 Input
- 4 Output
- 2, 3, 5 Ground

SIDE VIEW

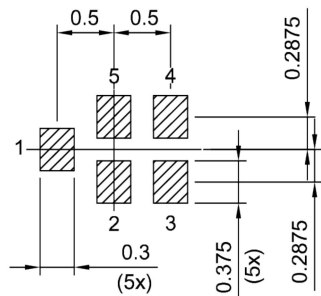


TOP VIEW



- 1) Marking for pad number 1
- 2) Example of encoded lot number
- 3) Example of encoded filter type number

Land pattern  
THRU VIEW



Landing pad tolerance  $-0.02$

**Figure 2:** Drawing of package with package height A = 0.45 mm (max.). See Sec. Package information (p. 20).

5 Matching circuit

■  $L_{p1} = 10 \text{ nH}$

■  $L_{s4} = 1.2 \text{ nH}$

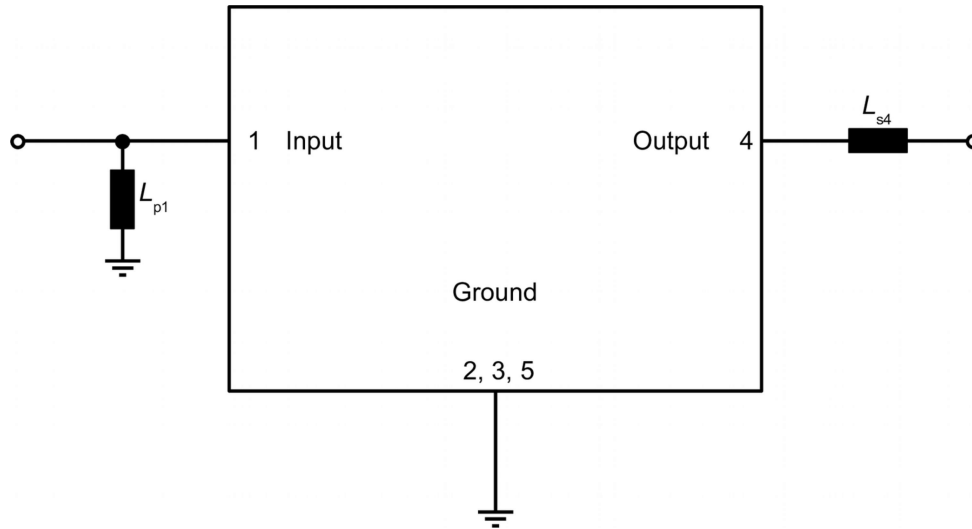


Figure 3: Schematic of matching circuit.

## 6 Characteristics

Temperature range for specification	$T_{SPEC}$	= -40 °C ... +85 °C
Input terminating impedance	$Z_{IN}$	= 50 $\Omega$ // 10 nH <sup>1)</sup>
Output terminating impedance	$Z_{OUT}$	= 50 $\Omega$ + 1.2 nH <sup>1)</sup>

Characteristics				min. for $T_{SPEC}$	typ. @ +25 °C	max. for $T_{SPEC}$		
<b>Center frequency</b>				$f_C$	—	2442	—	MHz
<b>Insertion attenuation – WLAN</b>				$\alpha_{WLAN}^{2)}$				
WLAN Channel 1	2403.1 ... 2420.9	MHz		—	1.9	2.7		dB
WLAN Channel 2	2408.1 ... 2425.9	MHz		—	1.7	2.2		dB
WLAN Channel 3-11	2413.1 ... 2470.9	MHz		—	1.4	2.0		dB
WLAN Channel 12	2458.1 ... 2475.9	MHz		—	1.6	2.2		dB
WLAN Channel 13	2463.1 ... 2480.9	MHz		—	1.8	2.7		dB
<b>Insertion attenuation – BT</b>				$\alpha_{BT}^{3)}$				
Bluetooth	2401.5 ... 2480.5	MHz		—	1.5	2.0		dB
<b>VSWR</b>								
@ input port	2403.1 ... 2475.9	MHz		—	1.6	2.3		
	2463.1 ... 2480.9	MHz		—	1.8	2.5		
@ output port	2403.1 ... 2475.9	MHz		—	1.6	2.3		
	2463.1 ... 2480.9	MHz		—	1.8	2.3		
<b>Attenuation</b>								
	100 ... 1805	MHz	$\alpha$	32	37	—		dB
	1805 ... 2170	MHz	$\alpha$	33	38	—		dB
	2300 ... 2360	MHz	$\alpha$	35	40	—		dB
	2360 ... 2365	MHz	$\alpha_{INT}^{4), 5)}$	38	42	—		dB
	2365 ... 2370	MHz	$\alpha_{INT}^{4), 5)}$	40	43	—		dB
	2370 ... 2375	MHz	$\alpha_{INT}^{4), 5)}$	35	45	—		dB
	2375 ... 2380	MHz	$\alpha_{INT}^{4), 5)}$	15	42	—		dB
	2500 ... 2505	MHz	$\alpha_{INT}^{4), 5)}$	43 <sup>6)</sup>	62	—		dB
	2500 ... 2505	MHz	$\alpha_{INT}^{4), 5)}$	26 <sup>7)</sup>	62	—		dB
	2505 ... 2570	MHz	$\alpha$	43	52	—		dB
	2570 ... 2620	MHz	$\alpha$	42	47	—		dB
	2620 ... 2690	MHz	$\alpha$	40	47	—		dB
	4800 ... 5850	MHz	$\alpha$	20	28	—		dB

<sup>1)</sup> See Sec. Matching circuit (p. 6).

<sup>2)</sup> Average over each WLAN channel with band width of 17.8 MHz.

<sup>3)</sup> Averaged value over whole pass band with band width of 79 MHz due to frequency hopping in Bluetooth mode.

<sup>4)</sup> Integrated over 5 MHz.

<sup>5)</sup> Averaged values of linear S-parameter over any 5MHz.

<sup>6)</sup> Valid for temperature  $T = +25\text{ °C} \dots +85\text{ °C}$ .

<sup>7)</sup> Valid for temperature  $T = -40\text{ °C} \dots +25\text{ °C}$ .

## 7 Maximum ratings

Operable temperature	$T_{OP} = -40\text{ °C} \dots +85\text{ °C}$	
Storage temperature	$T_{STG}^{1)} = -40\text{ °C} \dots +85\text{ °C}$	
DC voltage	$ V_{DC} ^{2)} = 0\text{ V (max.)}$	
Input power	$P_{IN}$	
@ input port: 2403.1 ... 2480.9 MHz	25 dBm	Continuous wave for 5000 h @ 85 °C. Source and load impedance 50Ω.
@ output port: 2403.1 ... 2480.9 MHz	22 dBm	Continuous wave for 5000 h @ 85 °C. Source and load impedance 50Ω.

<sup>1)</sup> Not valid for packaging material. Storage temperature for packaging material is -25 °C to +40 °C.

<sup>2)</sup> In case of applied DC voltage blocking capacitors are mandatory.



8 Transmission coefficient

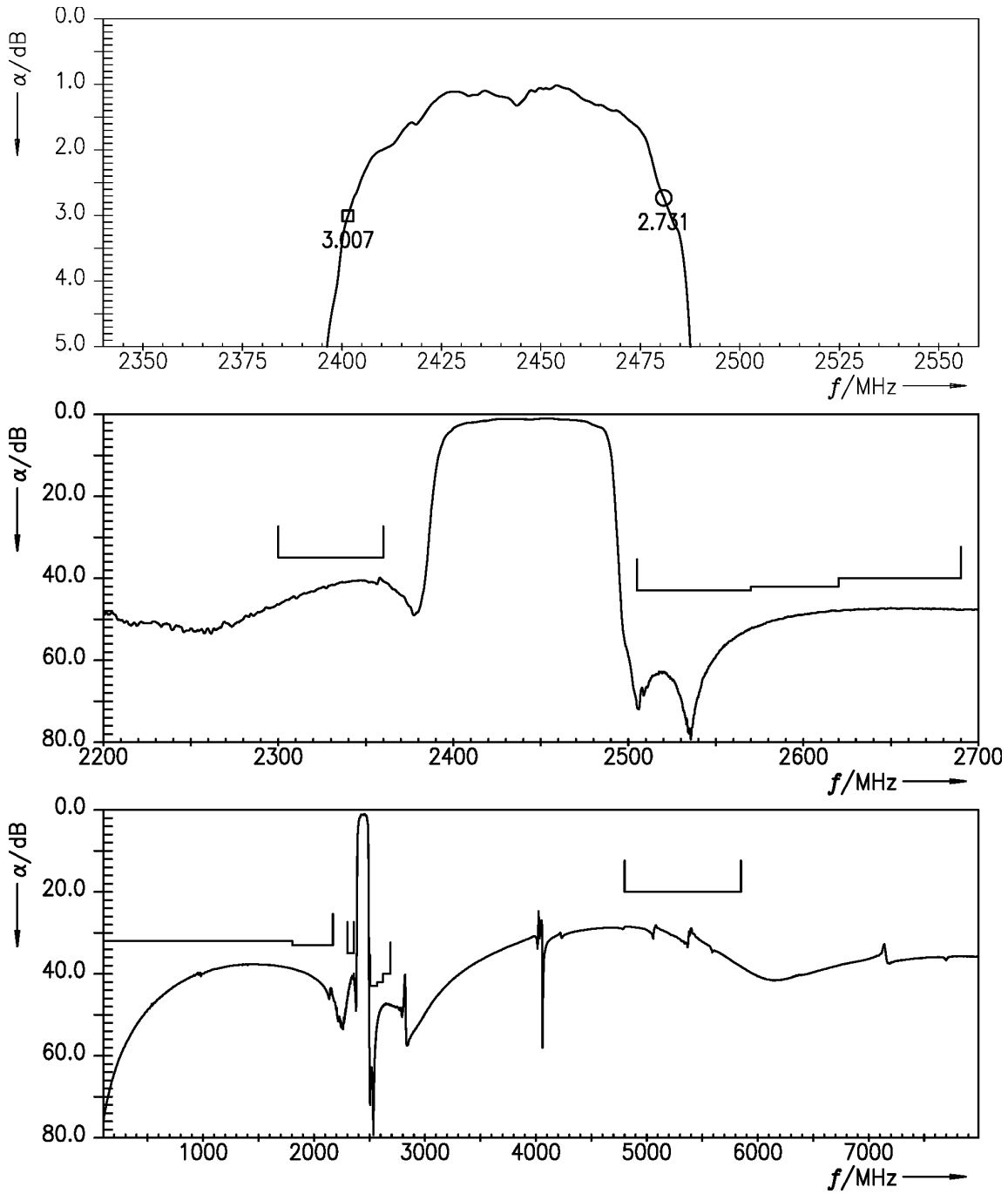


Figure 4: Attenuation.

9 Transmission coefficient (WLAN)

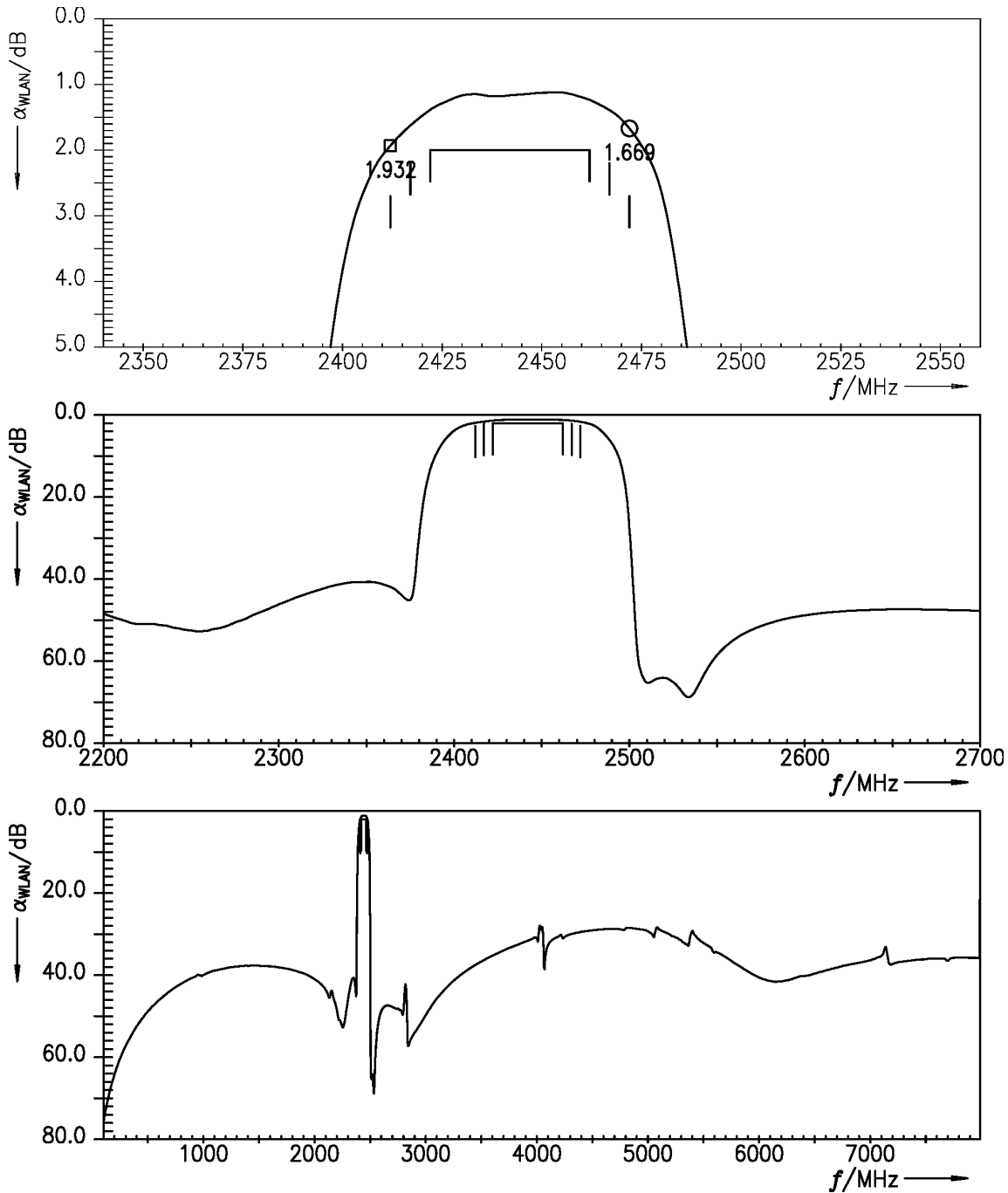


Figure 5: Attenuation (WLAN) (integration window = 17.8 MHz).

10 Transmission coefficient (BT)

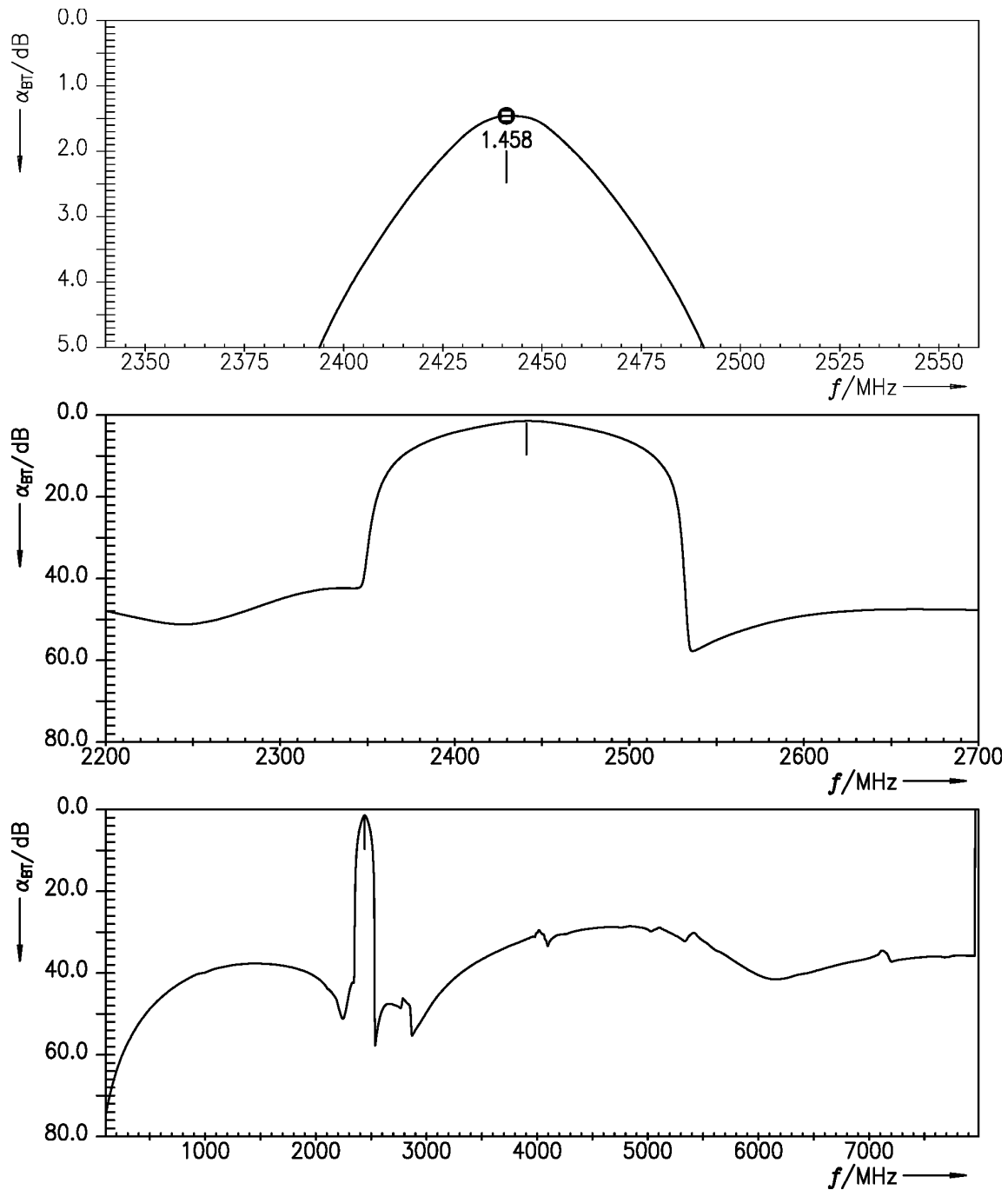


Figure 6: Attenuation (BT) (integration window = 79 MHz).

11 Transmission coefficient (integrated)

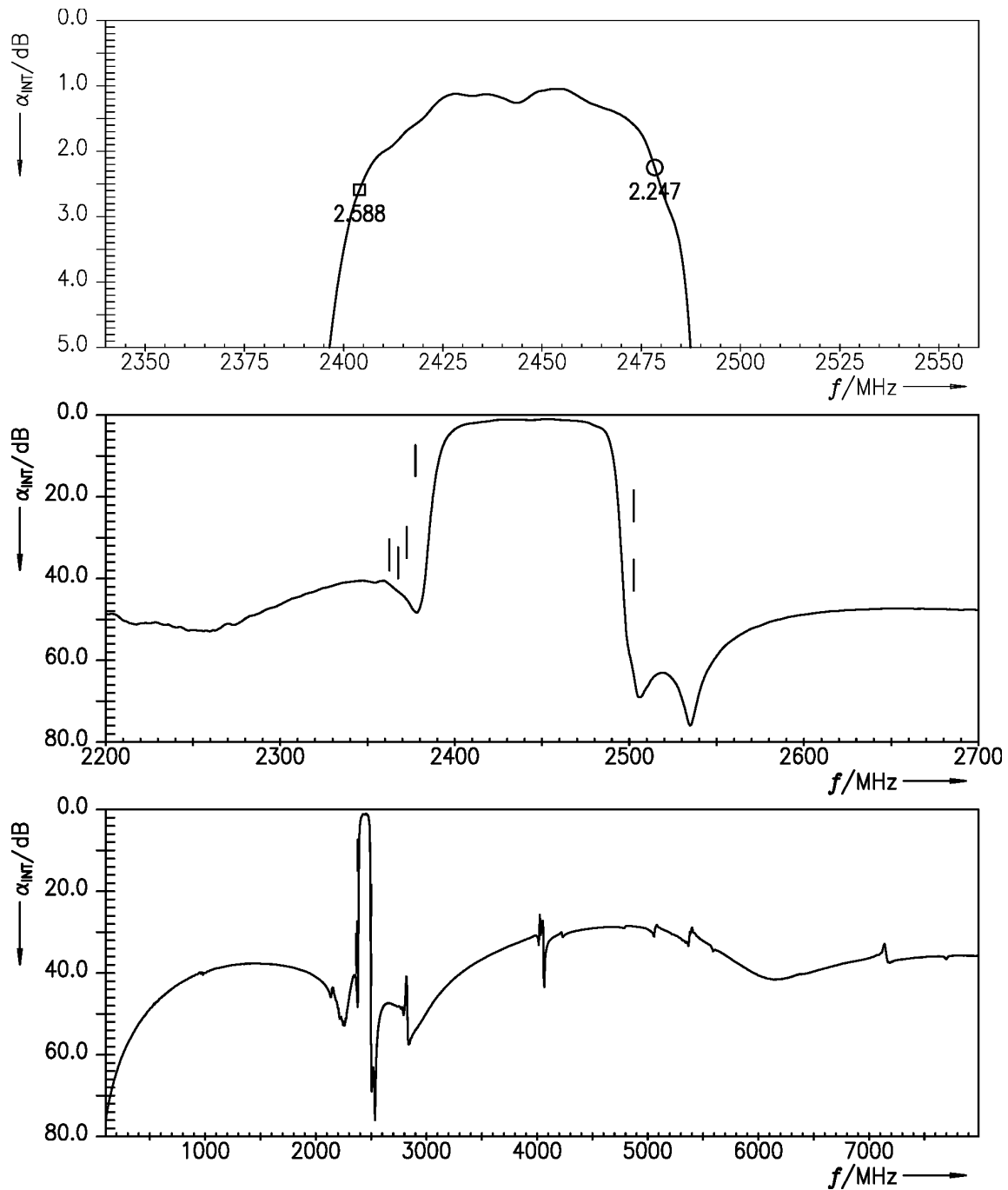


Figure 7: Integrated attenuation (integration window = 5 MHz).

12 Reflection coefficients

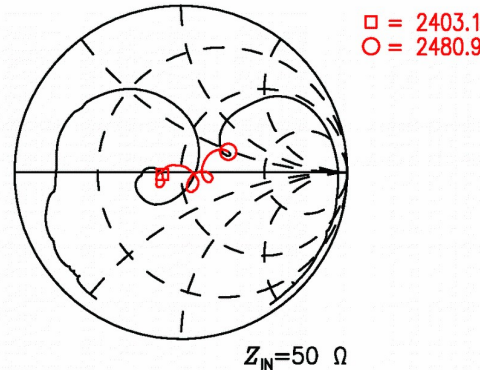
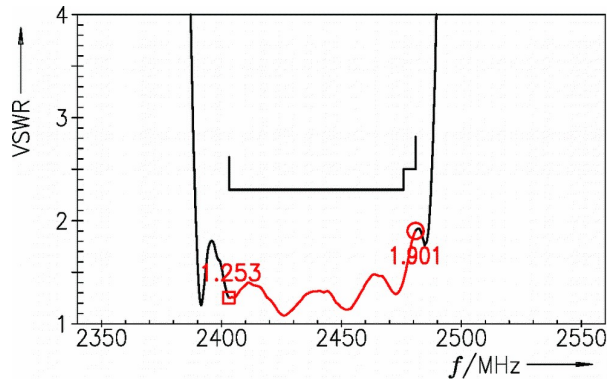


Figure 8: Reflection coefficient at input port.

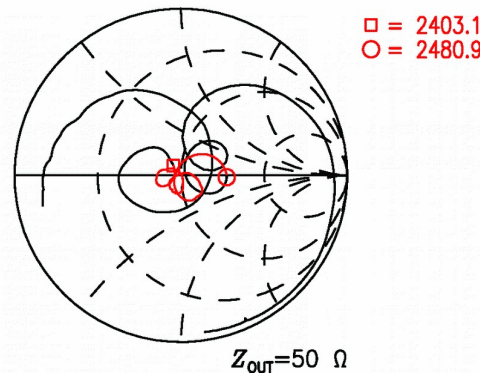
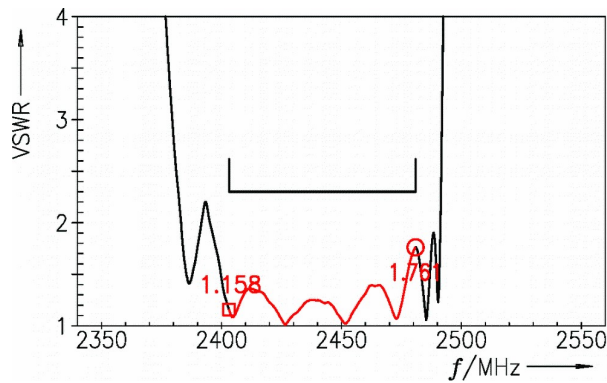
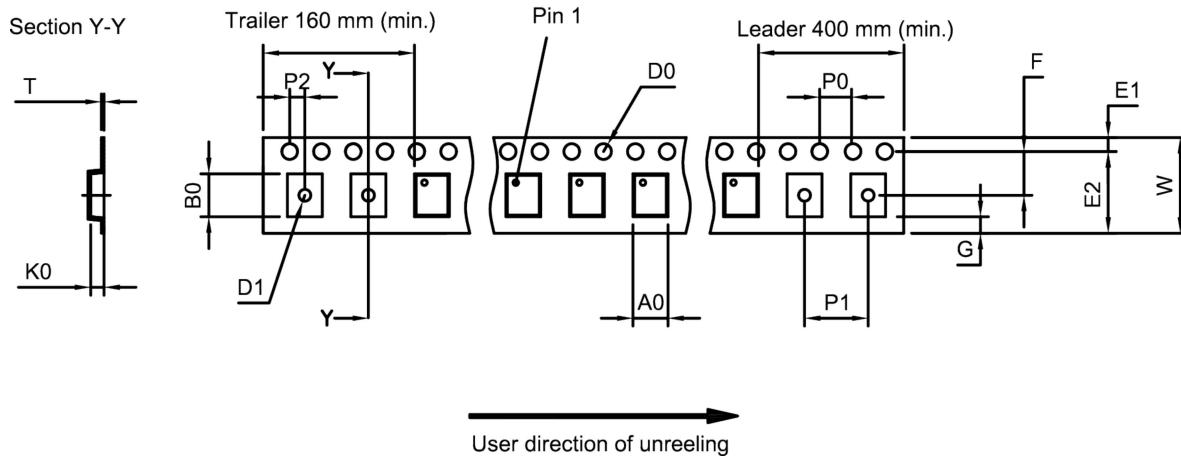


Figure 9: Reflection coefficient at output port.

13 Packing material

13.1 Tape



**Figure 10:** Drawing of tape (first-angle projection) for illustration only and not to scale. The valid tape dimensions are listed in Table 1.

$A_0$	1.27±0.05 mm	$E_2$	6.25 mm (min.)	$P_1$	4.0±0.1 mm
$B_0$	1.57±0.05 mm	F	3.5±0.05 mm	$P_2$	2.0±0.05 mm
$D_0$	1.5+0.1/-0 mm	G	0.75 mm (min.)	T	0.25±0.03 mm
$D_1$	0.5±0.1 mm	$K_0$	0.62±0.05 mm	W	8.0+0.3/-0.1 mm
$E_1$	1.75±0.1 mm	$P_0$	4.0±0.1 mm		

**Table 1:** Tape dimensions.

13.2 Reel with diameter of 180 mm

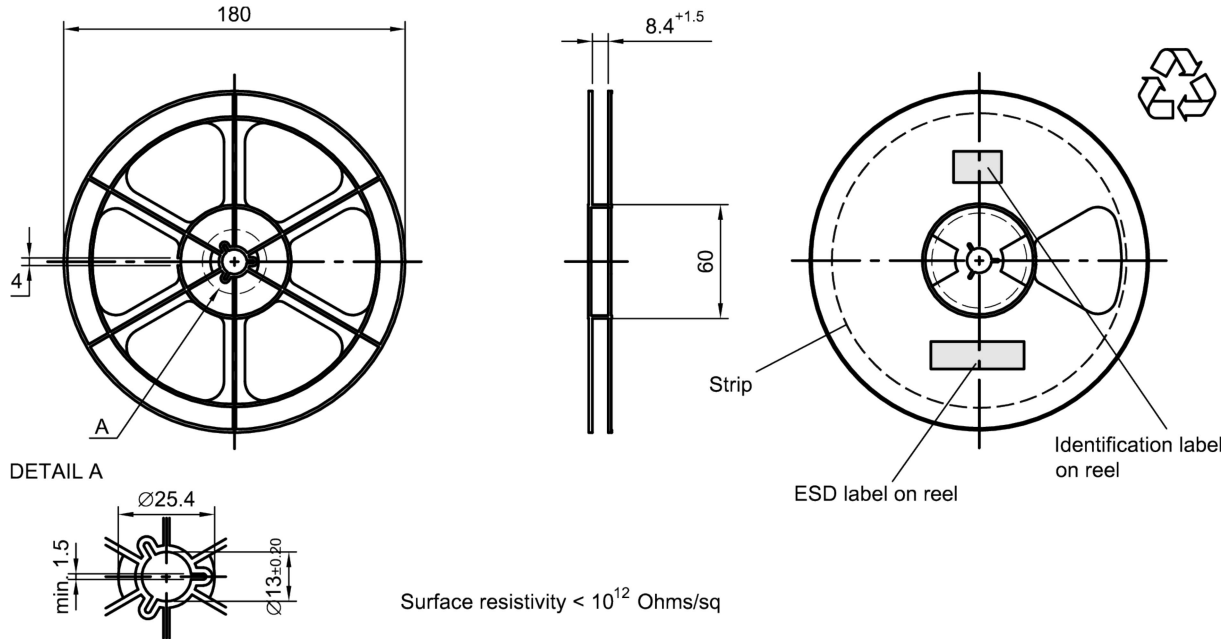


Figure 11: Drawing of reel (first-angle projection) with diameter of 180 mm.

Dimensions [mm]

X = 220+5

Y = 235+5

Sealing area 10±3

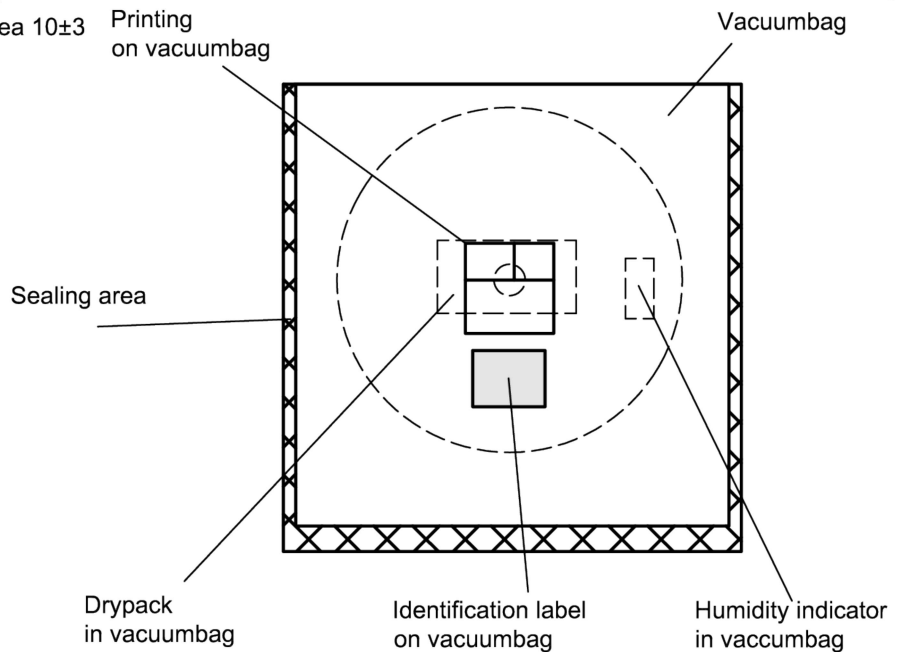
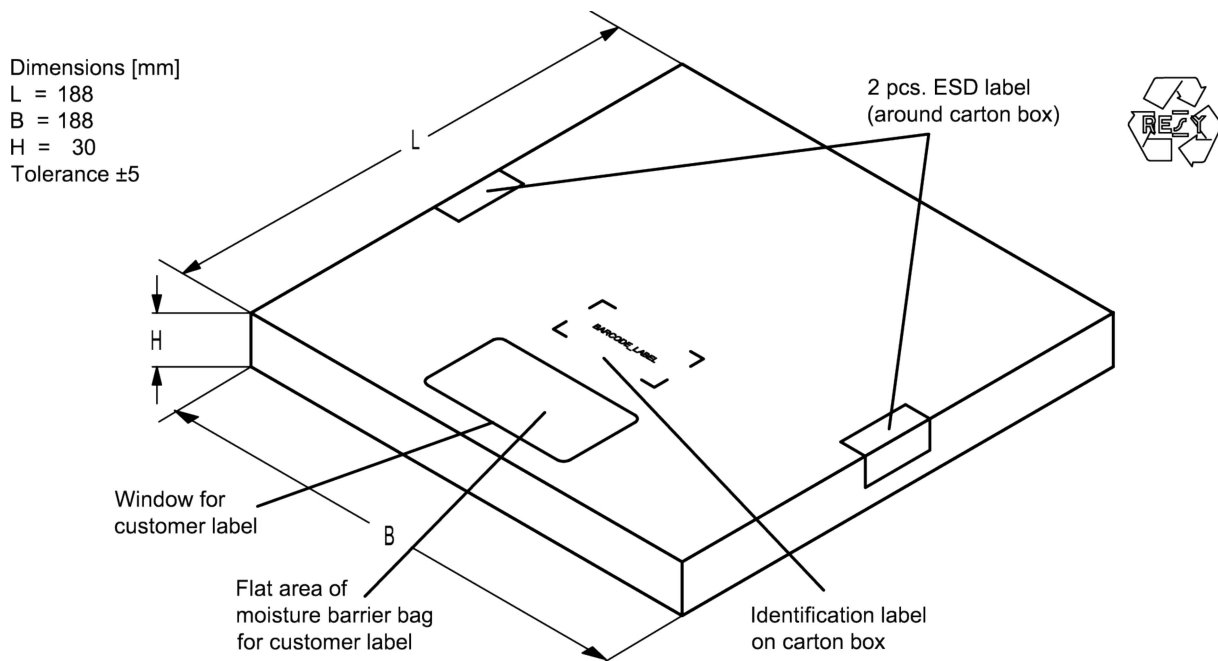


Figure 12: Drawing of moisture barrier bag (MBB) for reel with diameter of 180 mm.



**Figure 13:** Drawing of folding box for reel with diameter of 180 mm.



## 14 Marking

Products are marked with product type number and lot number encoded according to Table 2:

### ■ Type number:

The 4 digit type number of the ordering code, e.g., B3xxxxB**1234**xxxx,  
is encoded by a special BASE32 code into a 3 digit marking.

Example of decoding type number marking on device in decimal code.  
**16J** => **1234**  
 $1 \times 32^2 + 6 \times 32^1 + 18 (=J) \times 32^0$  = **1234**

The BASE32 code for product type B4346 is 47T.

### ■ Lot number:

The last 5 digits of the lot number, e.g., **12345**,  
are encoded based on a special BASE47 code into a 3 digit marking.

Example of decoding lot number marking on device in decimal code.  
**5UY** => **12345**  
 $5 \times 47^2 + 27 (=U) \times 47^1 + 31 (=Y) \times 47^0$  = **12345**

Adopted BASE32 code for type number			
Decimal value	Base32 code	Decimal value	Base32 code
0	0	16	G
1	1	17	H
2	2	18	J
3	3	19	K
4	4	20	M
5	5	21	N
6	6	22	P
7	7	23	Q
8	8	24	R
9	9	25	S
10	A	26	T
11	B	27	V
12	C	28	W
13	D	29	X
14	E	30	Y
15	F	31	Z

Adopted BASE47 code for lot number			
Decimal value	Base47 code	Decimal value	Base47 code
0	0	24	R
1	1	25	S
2	2	26	T
3	3	27	U
4	4	28	V
5	5	29	W
6	6	30	X
7	7	31	Y
8	8	32	Z
9	9	33	b
10	A	34	d
11	B	35	f
12	C	36	h
13	D	37	n
14	E	38	r
15	F	39	t
16	G	40	v
17	H	41	\
18	J	42	?
19	K	43	{
20	L	44	}
21	M	45	<
22	N	46	>
23	P		

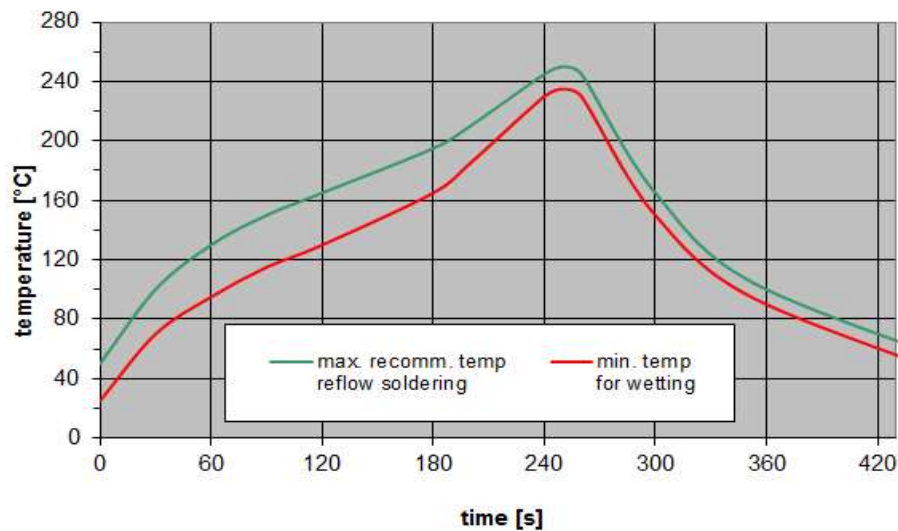
**Table 2:** Lists for encoding and decoding of marking.

### 15 Soldering profile

The recommended soldering process is in accordance with IEC 60068-2-58 – 3<sup>rd</sup> edit and IPC/JEDEC J-STD-020B.

ramp rate	≤ 3 K/s
preheat	125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s
T > 220 °C	30 s to 70 s
T > 230 °C	min. 10 s
T > 245 °C	max. 20 s
T ≥ 255 °C	–
peak temperature $T_{peak}$	250 °C +0/-5 °C
wetting temperature $T_{min}$	230 °C +5/-0 °C for 10 s ± 1 s
cooling rate	≤ 3 K/s
soldering temperature T	measured at solder pads

**Table 3:** Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).



**Figure 14:** Recommended reflow profile for convection and infrared soldering – lead-free solder.

## 16 Annotations

### 16.1 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

### 16.2 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local RF360 sales office.

## 17 Cautions and warnings

### 17.1 Display of ordering codes for RF360 products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of RF360, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under <https://rffe.qualcomm.com/>.

### 17.2 Material information

Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

For information on recycling of tapes and reels please contact one of our sales offices.

### 17.3 Moldability

Before using in overmolding environment, please contact your local RF360 sales office.

### 17.4 Package information

#### Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on RF360 internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of RF360, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

#### Dimensions

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

Dimensions do not include burrs.

#### Projection method

Unless otherwise specified first-angle projection is applied.

## 18 Important notes

The following applies to all products named in this publication:

1. Some parts of this publication contain **statements about the suitability of our products for certain areas of application**. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out **that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application**. As a rule, RF360 Europe GmbH and its affiliates are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether an RF360 product with the properties described in the product specification is suitable for use in a particular customer application.
2. We also point out that **in individual cases, a malfunction of electronic components or failure before the end of their usual service life cannot be completely ruled out in the current state of the art, even if they are operated as specified**. In customer applications requiring a very high level of operational safety and especially in customer applications in which the malfunction or failure of an electronic component could endanger human life or health (e.g. in accident prevention or life-saving systems), it must therefore be ensured by means of suitable design of the customer application or other action taken by the customer (e.g. installation of protective circuitry or redundancy) that no injury or damage is sustained by third parties in the event of malfunction or failure of an electronic component.
3. **The warnings, cautions and product-specific notes must be observed.**
4. In order to satisfy certain technical requirements, **some of the products described in this publication may contain substances subject to restrictions in certain jurisdictions (e.g. because they are classed as hazardous)**. Useful information on this will be found in our Material Data Sheets on the Internet (<https://rffe.qualcomm.com>). Should you have any more detailed questions, please contact our sales offices.
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